Product End-of-Life Disassembly Instructions

Marketing Name / Model
[List multiple models if applicable.]

HP RP9 G1 AiO Retail System, Model 9115

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by <em>(check all that apply with an “x” inside the “[ ]”)</em>: [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>LED</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

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<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>(gel/paste) and toner</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>0</td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td>0</td>
<td></td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philips Screwdriver</td>
<td>T15 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Slotted Screwdriver</td>
<td>2# 2.55-3.00kgf.cm</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Removed the base by loosening the latch.
2. Tore off the label of the case.
3. Pried open the case.
4. Removed the plastic frame.
5. Removed the metal sheet and tape of the plastic frame.
7. Removed the plastic case.
8. Removed the metal parts of the case.
9. Removed the metal frame.
10. Removed the metal frame by loosening 5 screws.
11. Removed the fan by loosening 3 screws.
12. Removed the metal frame for HDD by loosening 2 screws.
13. Removed the plastic parts of the metal frame by loosening 4 screws.
14. Removed the button cell.
15. Removed the side of PCB assembly by loosening 3 screws.
16. Removed the cable of the PCB assembly.
17. Removed the speaker.
18. Removed the antenna by loosened 2 screws.
19. Tore off sticker of the metal frame.
20. Loosened 9 screws of the PCB assembly.
21. Removed the PCB assembly.
22. Tore off the thermal pad of the metal frame.
23. Loosened 18 screws of the metal frame.
24. Removed the metal frame.
25. Separated the PCB assembly and plastic frame by removing cable.
26. Tore off the tape of LCD.
27. Removed the plastic frame of the panel.
28. Separated the touch panel and LCD.
29. Removed the FPC of the touch panel.
30. Removed the latch of the base by loosening 4 screws.
31. Removed the bracket of base by loosening 4 screws.
32. Separated the metal and plastic frame of the base - bracket.
33. Removed the plastic component of the joint part by loosening 2 screws.
34. Removed the tip pad by loosening 4 screws.
35. Opened the bottom cover by loosening 1 screw.
36. Tore off the thermal pad of the base.
37. Removed the side cover of the base.
38. Separated the base and stander by loosening 10 screws.
39. Pried open the plastic case of the joint parts.
40. Completed disassembly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Removed the base by loosening the latch.

Loosened 10 screws of the case.

Removed the plastic case.

Removed the metal frame for HDD by loosening 2 screws.

Tore off the label of the case.

Removal the metal sheet and tape of the plastic frame.

Removed the metal parts of the case.

Removed the metal frame by loosening 5 screws.
Removed the plastic parts of the metal frame by loosening 4 screws.

Removed the button cell. 移除按鈕電池。 (S.S.T.)

Removed the side of PCB assembly by loosening 3 screws.

Removed the antenna by loosened 2 screws.

Removed the speaker.

Removed the cable of the PCB assembly.

Tore off sticker of the metal frame.

Loosened 9 screws of the PCB assembly.

Removing the PCB assembly. (S.S.T.)

Removed the metal frame.

Loosened 18 screws of the metal frame.

Tore off the thermal pad of the metal frame.

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Separated the PCB assembly and plastic frame by removing cable.
移除電纜以分離塑膠框上的電路板。

Tore off the tape of LCD.
撕除 LCD 上的膠帶。

Removed the plastic frame of the panel.
移除面板的塑膠框。

Removed the latch of the base by loosening 4 screws.
鬆開 4 頭螺絲以移除底座上的卡榫。

Removed the FPC of the touch panel.
分離觸控面板上的 FPC。

Separated the touch panel and LCD.
分離觸控面板與 LCD。

Removed the bracket of base by loosening 4 screws.
鬆開 4 頭螺絲以移除底座上的托架。

Separated the metal and plastic frame of the base-bracket.
分離托架的金屬與塑膠框。

Removed the plastic component of the joint part by loosening 2 screws.
鬆開 2 頭螺絲以移除支架塑膠部件。

Tore off the thermal pad of the base.
移除底座的散熱座。

Opened the bottom cover by loosening 1 screw.
鬆開 1 頭螺絲以打開下底蓋。

Removed the tip pad by loosening 4 screws.
鬆開 4 頭螺絲以移除底蓋上的頂蓋。

Separated the base and stander by loosening 10 screws.
鬆開 10 頭螺絲以分離底座與支架。

Pried open the plastic case of the joint parts.
撬開支架上的塑膠殼。

Completed disassembly.
完成拆卸。

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